

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V.		BC847BPNH						
Name of Laboratory		Part Description						
		Nexperia DHAM	Small Signal B	Sipolar Transist	or			
Assembly reliability labs		SMD package						
Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST Pre- and Post-Stress							
# 1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
	PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	849	61170	0		
	HTRB High Temperature Reverse Bias	MIL-STD-750-1 M1039 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	202	16160	0		
	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	200 cycles	171	13680	0		
	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	173	13840	0		
	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage $^{[1]}$	1000 hours	173	13840	0		
	IOL Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	333 hours	197	15760	0		
# 20	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	135	4050	0		
	SD Solderability	J-STD-002		342	3420	0		

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia	Small Signal Bipolar				
DHAM	Transistor	16160	0	0.26	3.81E+09

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